



Material Content Data Sheet



Sales Product Name		IDH03SG60C		Issued		29. August 2013		
MA#		MA000629794						
Package		PG-TO220-2-1		Weight*		1966.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.013	0.00		6	
	non noble metal	tin	7440-31-5	0.003	0.00	0.03	2	289
	inorganic material	siliconcarbide	409-21-2	0.553	0.03		281	
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		683	
	inorganic material	phosphorus	7723-14-0	0.403	0.02		205	
	non noble metal	copper	7440-50-8	1341.263	68.22	68.31	682220	683108
wire	non noble metal	aluminium	7429-90-5	0.166	0.01	0.01	85	85
encapsulation	organic material	carbon black	1333-86-4	9.114	0.46		4636	
	plastics	epoxy resin	-	100.253	5.10		50993	
	inorganic material	silicondioxide	60676-86-0	498.228	25.34	30.90	253419	309048
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7369	7369
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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